

**Amendments to the Specification:**

Please insert the following on page 8 of the current specification after the sentence “Most commonly, said surface will be that of a dielectric layer, but that is not a requirement of the invention”:

The hole extends from an upper surface of the dielectric layer to a first wiring layer.

Please insert the following on page 8 of the current specification after the sentence “Typically the trench width used will be between about 0.1 and 15 microns, the hole diameter between about 0.1 and 0.5 microns, and the depth of the opening will be between 0.4 and 1 microns”:

The trench is formed by patterning and etching the dielectric layer. The trench comprises a bottom surface, a mouth, and side walls. In addition, the trench is disposed to fully overlap the hole and to extend a depth below the upper surface of the dielectric layer. The depth of the trench is greater than a depth of the hole, which extends a distance from the bottom surface of the trench to the first wiring layer.

Please insert the following on page 8 of the current specification after the sentence “Whether or not a barrier layer is used, a seed layer of metal (specifically copper if a damascene process is being used) is next laid down to cover the inside surfaces of the trench or hole”:

In addition to copper, the metal may be gold or silver.